

METAL BASE BOARD AND ELECTRONIC APPARATUS

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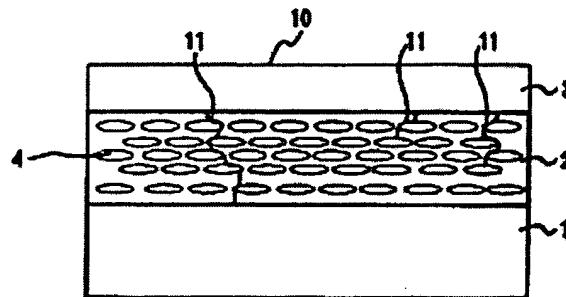
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Abstract of JP7050460

PURPOSE: To obtain a metal base board wherein heat dissipating characteristics of a board are excellent, application at a high voltage is possible, and resistance to discharge is large.

CONSTITUTION: In a metal base board 10 constituted of a metal board 1, circuit conductor 3, and an insulating layer 2 interposed between the circuit conductor 3 and a metal board 1, the insulating layer 2 is composed of organic insulating material to which inorganic filler 4 in a state of flake is added, and the inorganic filler 4 are laminated to improve resistance to discharge.

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